



Material Content Data Sheet



Sales Product Name		BSP762T		Issued		20. July 2018		
MA#		MA000975754						
Package		PG-DSO-8-24		Weight*		83.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.265	2.72	2.72	27177	27177
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8603	
wire	non noble metal	copper	7440-50-8	29.121	34.93	35.84	349335	358476
	noble metal	gold	7440-57-5	0.444	0.53	0.53	5331	5331
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165
encapsulation	plastics	epoxy resin	-	4.466	5.36		53569	
	inorganic material	silicondioxide	60676-86-0	43.976	52.75	58.23	527537	582271
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9763	9763
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7800	7800
glue	plastics	epoxy resin	-	0.134	0.16		1607	
	noble metal	silver	7440-22-4	0.631	0.76	0.92	7575	9182
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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